

## 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

# Notification# 20190916000 Datasheet for TPS3836, TPS3837, TPS3838 Information Only

**Date:** November 15, 2019 **To:** Newark/Farnell PCN

### Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

# Information Only Attachments

## **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	<b>CUSTOMER PART NUMBER</b>
TPS3838K33DBVT	null
TPS3836E18DBVT	null
TPS3836H30DBVT	null
TPS3836K33DBVT	null
TPS3836L30DBVT	null
TPS3837K33DBVT	null
TPS3838E18DBVR	null
TPS3838E18DBVT	null
TPS3838J25DBVT	null
TPS3836J25DBVT	null
TPS3838K33DBVR	null
TPS3838L30DBVT	null

Technical details of this Product Change follow on the next page(s).

DCN	I Nives borr	20100016000		DCN Datas	Nier	15 20	210	
	PCN Number:         20190916000         PCN Date:         Nov. 15, 2019           Title:         Datasheet for TPS3836, TPS3837, TPS3838							
Title			337, 17538	338			0 121 0 :	
	tomer Contact:	PCN Manager			De	pt:	Quality Services	
Cna	nge Type:		> ! - · ·			\\/- 6	D Cit-	
	Assembly Site		Design			Wafer Bump Site		
H	Assembly Process		Data Sheet		+	Wafer Bump Material Wafer Bump Process		
HH	Assembly Materials Mechanical Specification		Part number change		+		Fab Site	
H			Test Site Test Process		╅	Wafer Fab Materials		
	Packing/Shipping/Labeling Test Process Wafer Fab Materia Wafer Fab Process							
	Notification Details							
Des	cription of Chang		inicació	Details				
	as Instruments Inco		uncing an	information o	nlv no	otificatio	on.	
	product datasheet(					, in tour circ		
	following change h							
	3 3	, ,						
	TEXAS							
•	INSTRUMENTS			CI.	VENONE		6, TPS3837, TPS3838 -REVISED SEPTEMBER 2019	
_				- SL	.V0Z8ZF -	-JUNE 2000-	-REVISED SEPTEMBER 2019	
Cha	anges from Revision E (	October 2010) to Revis	sion F				Page	
	Changed format to meet	latest data sheet standa	ards: changed	data sheet title, a	dded D	evice Info	rmation table. Pin	
	Configurations and Funct							
	Implementation, Power S							
	Support Resources section	•						
	Changed 2x2 WSON to 2							
	Changed link to automoti							
	Added tall deferry market for the met deficition of Decempton decision							
	Changed 2x2 WSON to 2-mm × 2-mm WSON in last paragraph of Description section							
	_		-					
	Deleted soldering temperature parameter from Absolute Maximum Ratings table							
				•				
	Changed Handling Rating Added Thermal Informati							
	<ul> <li>Moved propagation (delay) time maximum values to the TYP column</li></ul>							
_	Changed propagation tim	les for the high-to-low-le	ever output an	a low-to-nigh-level	output	Irom: 0.1	μs το: 0.3 μs	
The	datasheet number	will be changing.						
	vice Family		Change I	From:		Change	e To:	
	,							
тро	S3836, TPS3837, T	DC3838	SLVS292	PE		SLVS2	92F	
					ļ			
These changes may be reviewed at the datasheet links provided.								
http://www.ti.com/product/TPS3836								
Reason for Change:								
To accurately reflect device characteristics.								
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								
No anticipated impact. This is a specification change announcement only. There are no changes								
	ne actual device.	a specifica	c.iaii	,		,		
Changes to product identification resulting from this PCN:								
None.								

<b>Product Affected:</b>			
TPS3836E18DBVR	TPS3836L30DBVR	TPS3837L30DBVR	TPS3838K33DBVR
TPS3836E18DBVT	TPS3836L30DBVRG4	TPS3837L30DBVT	TPS3838K33DBVRG4
TPS3836E18DBVTG4	TPS3836L30DBVT	TPS3837L30DBVTG4	TPS3838K33DBVT
TPS3836H30DBVR	TPS3836L30DBVTG4	TPS3838E18DBVR	TPS3838K33DBVTG4
TPS3836H30DBVT	TPS3837E18DBVT	TPS3838E18DBVRG4	TPS3838K33DRVR
TPS3836J25DBVR	TPS3837E18DBVTG4	TPS3838E18DBVT	TPS3838K33DRVT
TPS3836J25DBVT	TPS3837J25DBVR	TPS3838E18DBVTG4	TPS3838L30DBVR
TPS3836K33DBVR	TPS3837J25DBVT	TPS3838J25DBVR	TPS3838L30DBVRG4
TPS3836K33DBVRG4	TPS3837K33DBVR	TPS3838J25DBVRG4	TPS3838L30DBVT
TPS3836K33DBVT	TPS3837K33DBVT	TPS3838J25DBVT	TPS3838L30DBVTG4
TPS3836K33DBVTG4	TPS3837K33DBVTG4	TPS3838J25DBVTG4	

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com

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